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Intel® 6321ESB I/O Controller

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Code Name [Products formerly ESB2](#)

Status Launched

Launch Date  Q1'06

TDP  12.4 W

Recommended Customer Price  N/A

Supplemental Information

Embedded Options Available  Yes

Datasheet [View now](#)

Expansion Options

PCI Support  PCI (32/33) or PCI-X (66/100/133)

I/O Specifications

USB Revision  USB 2.0

of USB Ports 8

Total # of SATA Ports  6

Integrated LAN  Dual 10/100/1000

Integrated IDE  2 Channels

Package Specifications

Package Size 40mm x 40mm

Low Halogen Options Available See MDDDS

Advanced Technologies

Intel® ME Firmware Version  Yes

Intel® Quick Resume Technology  No

Intel® Quiet System Technology  No

Intel® HD Audio Technology  Yes

Intel® AC97 Technology  Yes

Intel® Matrix Storage Technology  No

Security & Reliability

Intel® Trusted Execution Technology

‡  No

Ordering and Compliance

Downloads and Software

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Refer to Datasheet for formal definitions of product properties and features.

"Announced" SKUs are not yet available. Please refer to the Launch Date for market availability.

‡ This feature may not be available on all computing systems. Please check with the system vendor to determine if your system delivers this feature, or reference the system specifications (motherboard, processor, chipset, power supply, HDD, graphics controller, memory, BIOS, drivers, virtual machine monitor-VMM, platform software, and/or operating system) for feature compatibility. Functionality, performance, and other benefits of this feature may vary depending on system configuration.

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System and Maximum TDP is based on worst case scenarios. Actual TDP may be lower if not all I/Os for chipsets are used.

Low Halogen: Applies only to brominated and chlorinated flame retardants (BFRs/CFRs) and PVC in the final product. Intel components as well as purchased components on the finished assembly meet JS-709 requirements, and the PCB / substrate meet IEC 61249-2-21 requirements. The replacement of halogenated flame retardants and/or PVC may not be better for the environment.

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